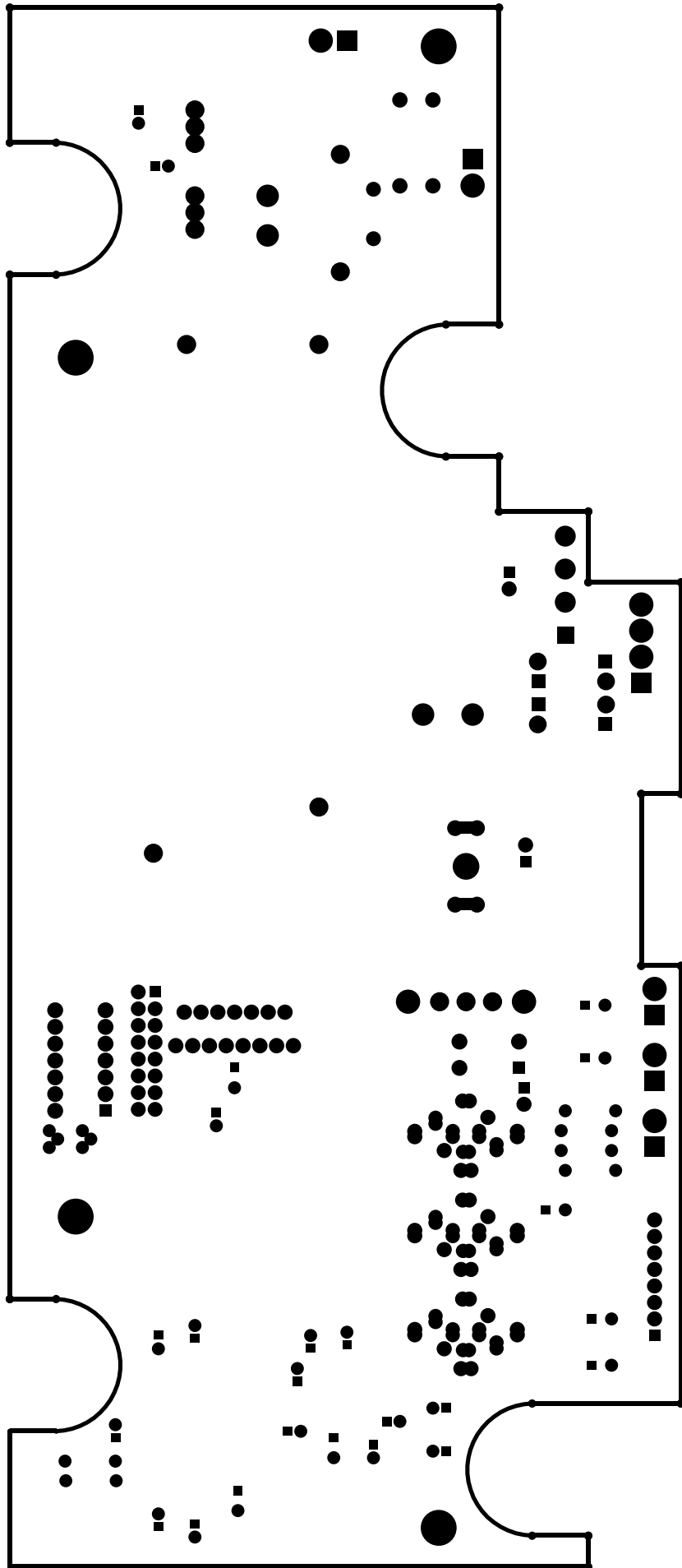
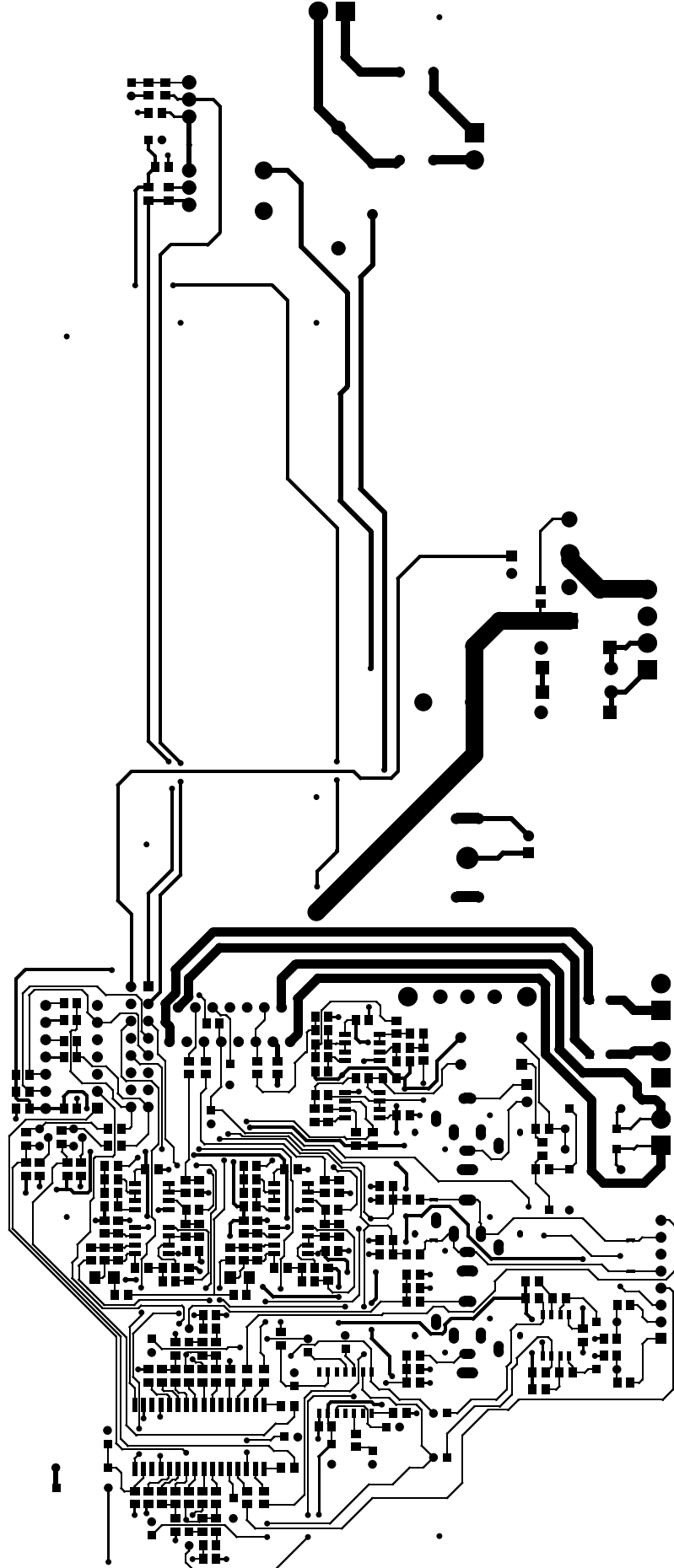


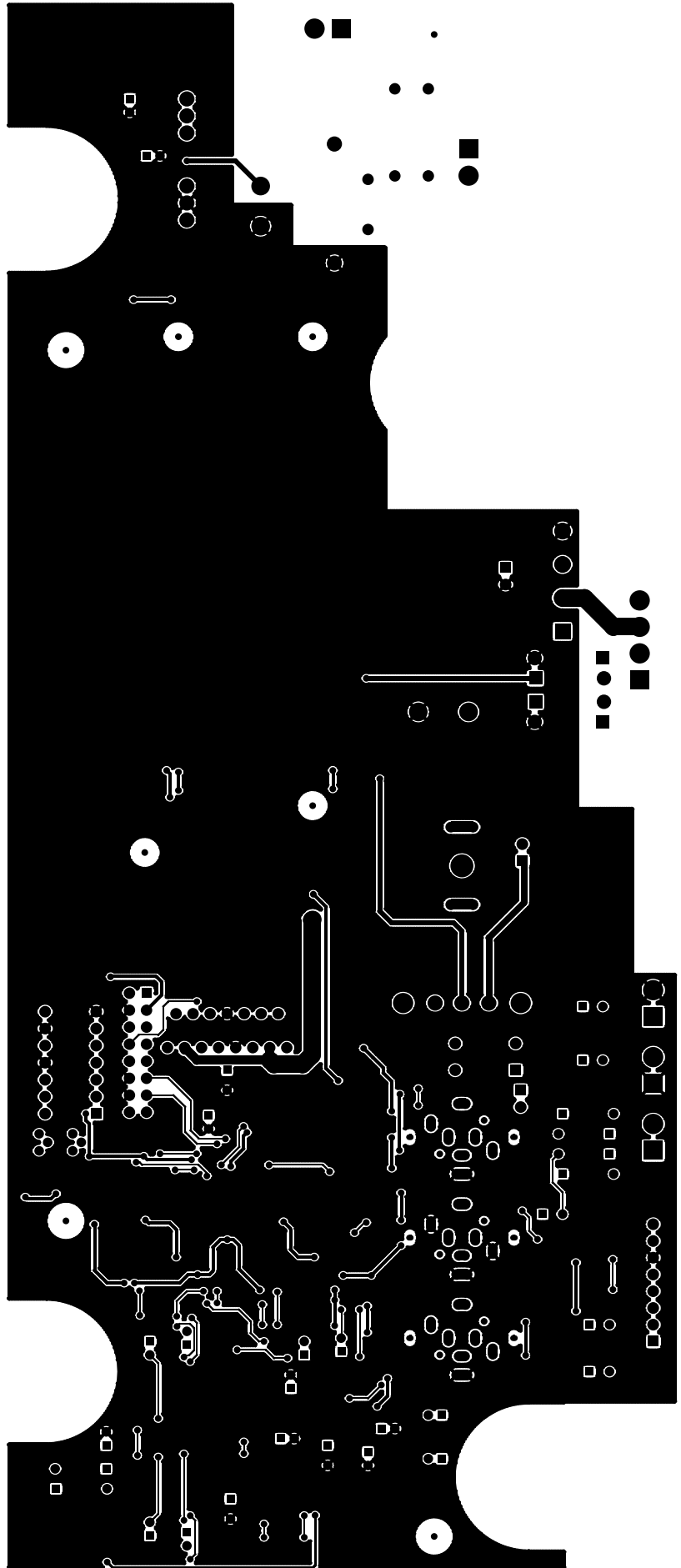
LAYER Secondary Side Soldermask



LAYER	Primary Side Soldermask
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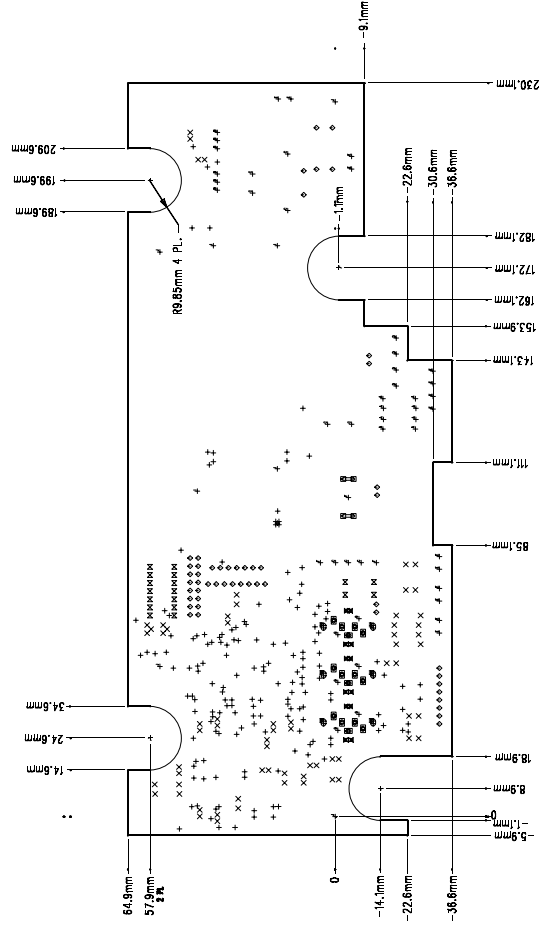


LAYER 2 Secondary Side



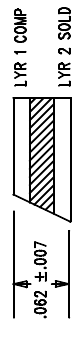
LAYER 1	Primary Side
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J	.177	±.005	4	NO
I	.080	±.005	4	NO
H	DAMP WIRE SLOT BETWEEN THE HOLE WALLS AND FOR ENDSHIMS			
G	.055	±.005	6	NO
F	.090	±.005	3	YES
E	.070	±.005	14	YES
D	.062	±.005	4	YES
C	.052	±.005	6	YES
B	.050	±.005	8	YES
A	.047	±.005	8	YES
M	.040	±.005	18	YES
X	DAMP WIRE SLOT IN HOLE THE HOLE WALLS AND ENDSHIMS			
□	.038	±.005	51	YES
◇	DAMP WIRE SLOT IN HOLE THE HOLE WALLS AND ENDSHIMS			
X	.027	±.005	66	YES
+	.013	±.005	166	YES
SYM	HOLE DIAMETER		QTY	PLATED
HOLE TOLERANCES APPLY AFTER PLATING				
HOLE LEGEND				



NOTES:

1. LAYER ORIENTATION.



2. MATERIAL: FR4, G10, OR MULTI-FUNCTIONAL EPOXY GLASS OR EQUIVALENT.
1/2 OZ. CU CLAD.
0.062" ±/ - 0.006" (FINISHED).
3. THICKNESS: - 1/2 OZ. PLATED TO 1 1/2 OZ. ON OUTER LAYERS.
4. PLATING: - ALL PLATED THROUGH HOLES TO HAVE A MINIMUM BARREL THICKNESS OF 0.025 mm. (0.001").
SN/PB (TIM/LEAD) PLATE RATIO = 63/37
LIQUID PHOTO-IMAGEABLE MASK OVER BARE COPPER.
5. FINISH: USE CONTRASTING EPOXY INK.
6. SOLDERMASK: MINIMUM TRACE WIDTH = 0.012"
MINIMUM TRACE SPACING = 0.012"
7. SILKSCREEN: MINIMUM = 0.007"/IN
8. ARTWORK: MAXIMUM = 0.007"/IN
9. BOW AND TWIST: